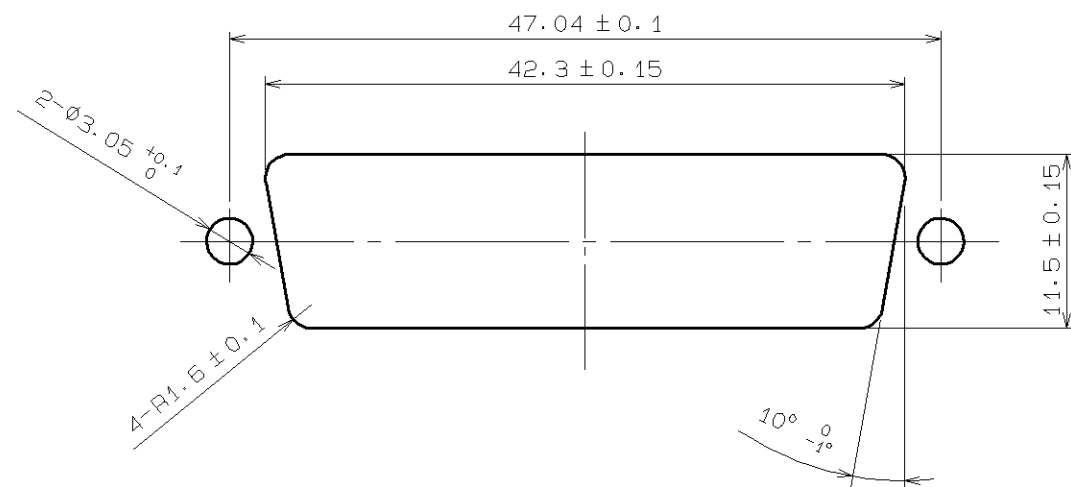
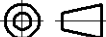




PANEL CUTOUT



NOTE 1. SOLDERING SHALL BE DOWN WITH SOLDERING BIT OF 40W MAX WITHIN 4s.
2. CONTACT AREA: GOLD PLATING $0.2\mu\text{m}$ MIN
TERMINAL AREA: GOLD PLATING $0.03\mu\text{m}$ MIN
UNDERPLATING: NICKEL PLATING $1\mu\text{m}$ MIN

3	PBT	UL94V-0 BLACK							
2	PBT	UL94V-0 BLACK		5	STEEL	NICKEL PLATING 2μm			
1	PHOSPHOR BRONZE	2		4	STEEL	NICKEL PLATING 2μm			
NO.	MATERIAL	FINISH. REMARKS		NO.	MATERIAL	FINISH. REMARKS			
UNITS mm		SCALE 2 : 1		COUNT	DESCRIPTION OF REVISIONS		DESIGNED	CHECKED	DATE
 HIROSE ELECTRIC CO., LTD.		APPROVED : HO.MIWA	06.07.26		DRAWING NO.		EDC3-009499-02		
		CHECKED : HO.MIWA	06.07.26		PART NO.		HDBB-25P(05)		
		DESIGNED : YH.ENAMI	06.07.26		CODE NO.		CL211-0215-7-05		
		DRAWN : YH.ENAMI	06.07.26						
						